



## Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model  
[List multiple models if applicable.]

HP ZBook 15 G6 Mobile Workstation

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

**NOTE:** Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact [HP's Sustainability Contact](#).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries, excluding Li-Ion batteries.	All types including standard alkaline, coin or button style batteries	1
Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)	Battery(ies) are attached to the product by ( <i>check all that apply with an "x" inside the "[ ]"</i> ): [     ] screws [X] snaps [     ] adhesive [     ] other. Explain _____ NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords	DC Cable for External Power Supply	1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs)		

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HPI instructions for this template are available at [EL-MF877-01](#)

Item Description	Notes	Quantity of items included in product
already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
#1 screwdriver	+
#2 screwdriver	T8

## 3.0 Product Disassembly Process

**3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:**

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Relax to disassembly service door
2. Relax to disassembly main battery/RAM
3. Remove screw\*3 to disassembly HDD assy
4. Remove screw\*1 to disassembly Wlan module
5. Remove screw\*1 to disassembly Wwan module
6. Remove screw\*1 to disassembly SSD module
7. Remove screw\*3 to disassembly KB
8. Remove screw\*16 to disassembly Top-assy and Base-assy
9. Remove FFC, cable, antenna & connector on chassis side: Power/TP module/Finger printer/Speaker/antenna/dream color/NFC module/smart card/cables
10. Remove screw\*5 to disassembly thermal fan
11. Remove screw\*8 to disassembly main board
12. Remove screw\*6 to disassembly hinge-up on Top-assy
13. Remove screw\*3 to disassembly speaker assy on Top-assy
14. Remove screw\*1 to disassembly finger printer on Top-assy
15. Remove screw\*3 to disassembly Smart card reader on Top-assy
16. Remove screw\*4 to disassembly TP module on Top-assy
17. Remove screw\*2 to disassembly power daughter board on Top-assy
18. Disassembly Bezel-assy with LCD Cover-assy
19. Remove screw\*4 to disassembly Panel on Cover-assy
20. Removed screw\*8 to disassembly hinge on Cover-assy

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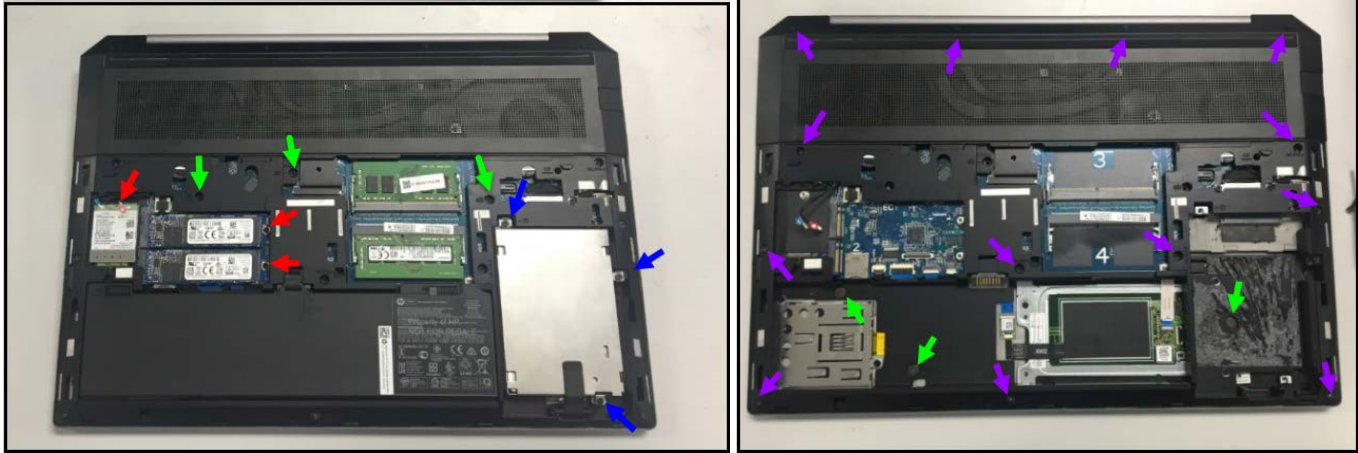
**Last revalidation date 09-May-2018**

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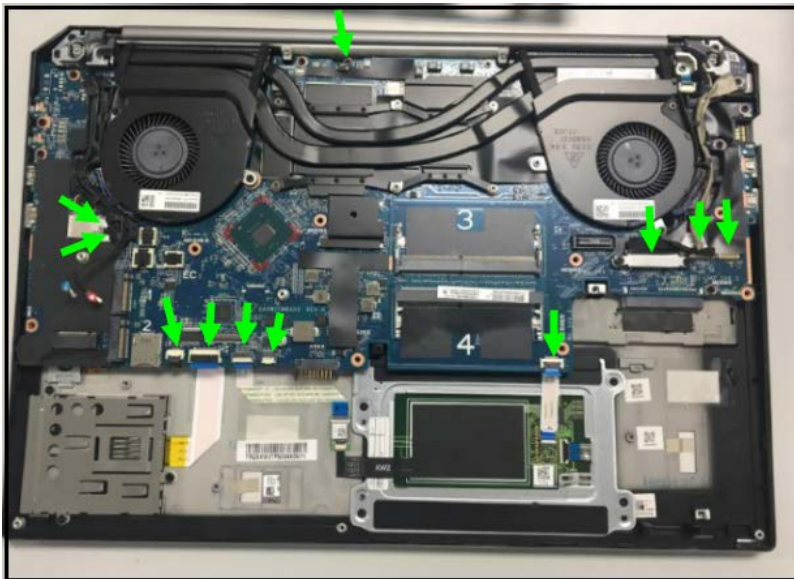
21. Removed Cable : LVDS 、 Antenna

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

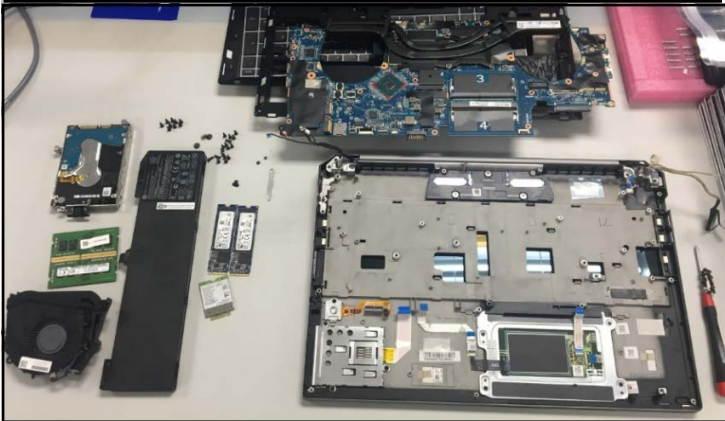
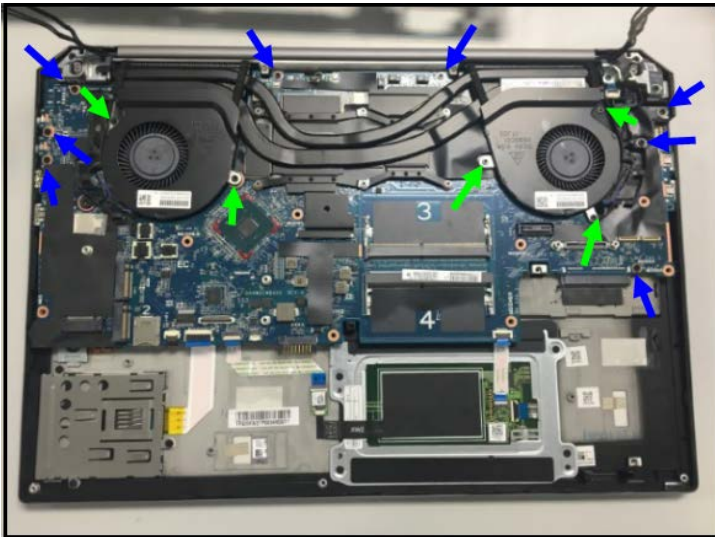
1. Remove screw to disassembly HDD, Wlan, Wwan, SSD, KB and base's screw.



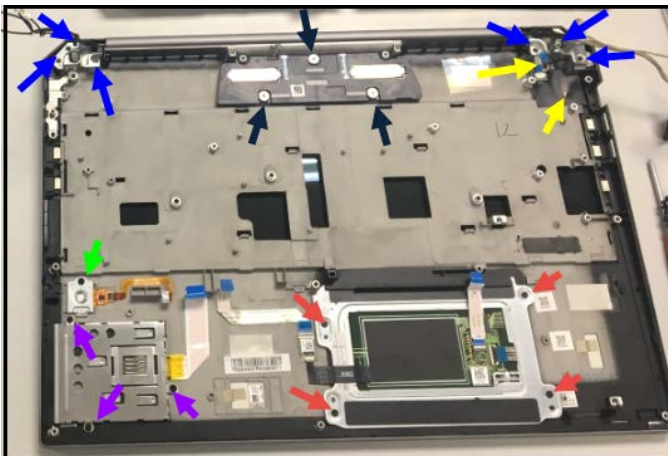
2. Remove FFC, cable, antenna & connector on chassis side: Power/TP module/Finger printer/Speaker/antenna/dream color/NFC module/smart card/cables



3. Remove screw\*5 to disassembly thermal fan/ Remove screw\*8 to disassembly main board

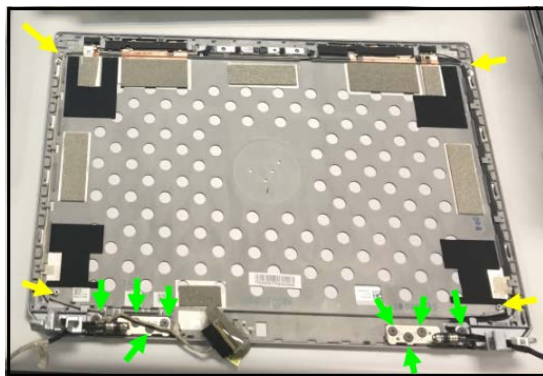


4. Remove screw to disassembly hinge-up/speaker/power board/finger printer/smart card read/ TP module on top-assy





5. Disassembly Bezel-assy / panel / hinge / cable / antenna with LCD Cover-assy



6. Totally disassembly parts

